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## (54) METHOD OF MANUFACTURING PRINTED WIRING BOARD

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#### (57)**ABSTRACT**

In a method of manufacturing a printed wiring board with a pattern formed using a printing process, a pattern of a portion requiring position accuracy can be accurately formed at a predetermined position.

A method of manufacturing a printed wiring board 10 according to the present invention includes preparing a laminated board 12 including a metal layer 16 formed on a surface of a base material 14, forming a first etching resist layer 20a by printing a pattern of a portion 18a requiring position accuracy on the metal layer of the laminated board using a metal mask 32, forming a second etching resist layer 20b by printing a pattern of a portion 18b other than the portion requiring position accuracy on the metal layer of the laminated board using a screen plate 34, removing, by etching, the metal layer of the laminated board where the first etching resist layer and the second etching resist layer are not formed, and stripping the first etching resist layer and the second etching resist layer.

